

# Liang He

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## Research Interests

My research interests lie in the field of human-computer interaction (HCI), including digital fabrication, tactile and haptic interfaces, tangible interaction, accessibility, and physical intelligence. I develop enabling tools, techniques, and devices that mediate and enhance human interaction with physical and virtual objects and environments. My research focuses on

- developing computational design tools and fabrication techniques to augment physical properties of objects with interactivity to enhance hand- and body-interactions (e.g., haptic interface, wearables, assistive devices)
- creating intelligent systems to empower end-users with less expertise in specialized tasks (e.g., 3D modeling, circuit prototyping)
- exploring electro-mechanical and material approaches to embed intelligence in physical objects and environments (e.g., robotics, sensing)

## Employment

- 8/2022–Present **Assistant Professor (tenure-track)**  
*Purdue University, Department of Computer Graphics Technology*  
Director of [Design & Engineering for Making \(DE4M\) Lab](#)
- 8/2024–Present **Affiliate Faculty**  
*Purdue University, Applied AI Research Center*
- 10/2020–12/2020 **Research Intern** with *Kris J. Erickson and Rafael 'Tico' Ballagas*  
*3D Print Lab, HP Labs, Palo Alto, CA*
- 6/2019–9/2019 **Research Intern** with *Rafael 'Tico' Ballagas*  
*Artificial Intelligence & Emerge Computing Lab, HP Labs, Palo Alto, CA*
- 6/2016–8/2016 **Research Intern** with *Rob DeLine and Saleema Amershi*  
*Microsoft Research, Redmond, WA*
- 5/2014–8/2014 **Research Intern** with *Ellen Yi-Luen Do and Beryl Plimmer*  
*Keio-NUS CUTE Center, Singapore*

## Education

- 7/2022 **Ph.D., Computer Science & Engineering**, University of Washington, Seattle  
Dissertation: Fabricating Kinetic Objects with 3D Printable Spring-Based Mechanisms for Interactivity  
Advisor: Jon E. Froehlich  
Committee members: Jennifer Mankoff, Adriana Schulz, and Nadya Peek  
(Transferred from the University of Maryland, College Park to UW in 2017)
- 5/2015 **M.S., Computational Design**, Carnegie Mellon University, Pittsburgh  
Thesis: SqueezaPulse - Adding Interactive Input Using Passive Pulses of Air
- 5/2013 **M.S., Computer Science and Technology**, University of Chinese Academy of Sciences  
Thesis: A Tangible Approach for Storytelling
- 5/2010 **B.Eng, Software Engineering**, Beihang University (BUAA)



## Publications

My students and myself are underlined.

### Conference Papers

- 2024 [C.11] **MobiPrint: A Mobile 3D Printer for Environment-Scale Design and Fabrication.** Daniel Campos Zamora, Liang He, and Jon E. Froehlich. In *Proceedings of the 37th Annual ACM Symposium on User Interface Software and Technology (UIST '24)*.
- 2023 [C.10] **3D Printing Magnetophoretic Display.** Zeyu Yan, Hsuanling Lee, Liang He, and Huaishu Peng. In *Proceedings of the 36th Annual ACM Symposium on User Interface Software and Technology (UIST '23)*.
- 2022 [C.9] **Kinergy: Creating 3D Printable Motion using Embedded Kinetic Energy.** Liang He, Xia Su, Huaishu Peng, Jeffrey I. Lipton, and Jon E. Froehlich. In *Proceedings of the 35th Annual ACM Symposium on User Interface Software and Technology (UIST '22)*.
- [C.8] **FlexHaptics: A Design Method for Haptic Inputs Using Flat Compliant Structures.** Hongnan Lin, Liang He, Fangli Song, Yifan Li, Tingyu Chen, Clement Zheng, Wei Wang, and HyunJoo Oh. In *Proceedings of the 40th Annual ACM Conference on Human Factor in Computing Systems (CHI '22)*.
- 2021 [C.7] **HulaMove: Using Commodity IMU for Waist Interaction.** Xuhai Xu, Jiahao Li, Tianyi Yuan, Liang He, Xin Liu, Yukang Yan, Yuntao Wang, Yuanchun Shi, Jennifer Mankoff, and Anind K. Dey. In *Proceedings of the 39th Annual ACM Conference on Human Factors in Computing Systems (CHI '21)*.
- 2019 [C.6] **Ondulé: Designing and Controlling 3D Printable Springs.** Liang He, Huaishu Peng, Michelle Lin, Ravikanth Konjeti, François Guimbretière, and Jon E. Froehlich.

In *Proceedings of the 32nd Annual ACM Symposium on User Interface Software and Technology (UIST '19)*.

- 2017 [C.5]  **MakerWear: A Tangible Approach to Interactive Wearable Creation for Children.** Majeed Kazemitabaar, Jason McPeak, Alexander Jiao, [Liang He](#), Thomas Outing, and Jon E. Froehlich. In *Proceedings of the 35th annual ACM conference on Human factors in computing systems (CHI '17)*.  
**Best Paper Award [Top 1%]**
- [C.4] **SqueezaPulse: Adding Interactive Input to Fabricated Objects Using Corrugated Tubes and Air Pulses.** [Liang He](#), Gierad Laput, Eric Brockmeyer, and Jon E. Froehlich. In *Proceedings of the ACM symposium on tangible and embodied interaction (TEI '17)*.
- 2015 [C.3] **PneuHaptic: Delivering Haptic Cues with a Pneumatic Armband.** [Liang He](#), Cheng Xu, Ding Xu, and Ryan Brill. In *Proceedings of the 19th International Symposium on Wearable Computers (ISWC '15)*.
- [C.2] **CozyMaps: Real-time Collaboration on a Shared Map with Multiple Displays.** Kelvin Cheng, [Liang He](#), Xiaojun Meng, David A. Shamma, Dung Nguyen, and Anbarasan Thangapalam. In *Proceedings of the 17th International Conference on Human-Computer Interaction with Mobile Devices and Services (MobileHCI'15)*.
- [C.1]  **New Interaction Tools for Preserving an Old Language.** Beryl Plimmer, [Liang He](#), Tariq Zaman, Kasun Karunanayaka, Alvin W. Yeo, Garen Jengan, Rachel Blagojevic, and Ellen Yi-Luen Do. In *Proceedings of the 33rd annual ACM conference on Human factors in computing systems (CHI '15)*.  
**Honorable Mentions Award [Top 3%]**

## Journal Papers


- 2021 [J.2] **ModElec: A Design Tool for Prototyping Physical Computing Devices Using Conductive 3D Printing.** [Liang He](#), Jarrid A. Wittkopf, Ji Won Jun, Kris Erickson, and Rafael 'Tico' Ballagas. In *Proceedings of the ACM on Interactive, Mobile, Wearable and Ubiquitous Technologies (IMWUT)* 5, no. 4 (2021): 1-20.
- 2014 [J.1] **StoryCube: Supporting Children's Storytelling with a Tangible Tool.** Danli Wang, [Liang He](#), and Keqin Dou. *The Journal of Supercomputing*, Volume 70 Issue 1, Pages 269-283. Springer. 2014.

## Dissertation & Doctoral Position Paper

- 2022 [Diss.] **Fabricating Kinetic Objects with 3D Printable Spring-Based Mechanisms for Interactivity.** [Liang He](#). University of Washington, 2022.
- 2020 [DC.1] **Designing, Controlling, and Fabricating In-Place Augmented Structures.** [Liang He](#). In *Adjunct Proceedings of the 33rd Annual ACM Symposium on User Interface Software and Technology (UIST '20 Doctoral Symposium)*.

Committee: Michel Beaudouin-Lafon, Ranjitha Kumar, Pedro Lopes, Camille Moussette, Ken Hinckley


## ***Extended Abstracts/Poster & Workshop Papers***

- 2024 [P.11] **Towards Rapid Fabrication of Custom Tactile Surface Indicators for Indoor Navigation.** Daniel Campos Zamora, [Liang He](#), and Jon E. Froehlich. In *Proceedings of the 26th International ACM SIGACCESS Conference on Computers and Accessibility (ASSETS '24)*.
- [P.10]  **Fluxable: A Tool for Making 3D Printable Sensors and Actuators.** [Hsuanling Lee](#), Yujie Shan, Huachao Mao, and [Liang He](#). In *Adjunct Proceedings of the 37th Annual ACM Symposium on User Interface Software and Technology (UIST Adjunct '24)*.  
**Best Poster Award [Top 1%]**
- [P.9] **3D Printing Shape-Changing Devices with Inductive Sensing.** [Hsuanling Lee](#) and [Liang He](#). In *ACM SIGGRAPH 2024 Posters (SIGGRAPH '24)*.
- 2023 [P.8] **A Multi-modal Toolkit to Support DIY Assistive Technology Creation for Blind and Low Vision People.** [Liwen He](#), [Yifan Li](#), Mingming Fan, [Liang He](#), and Yuhang Zhao. In *Adjunct Proceedings of the 36th Annual ACM Symposium on User Interface Software and Technology (UIST '23 Adjunct)*.
- [P.7] **Understanding the Experiences, Challenges, and Needs of Dementia Caregivers in the Indian Subcontinent.** [Srishti Shekhar Agrawal](#), [Shrey Panchal](#), and [Liang He](#). In *the 25th International ACM SIGACCESS Conference on Computers and Accessibility (ASSETS '23)*.
- 2022 [D.1] **sPrintr: Towards In-Situ Personal Fabrication using a Mobile 3D Printer.** Daniel Campos Zamora, [Liang He](#), Yueqian Zhang, Xuhai Xu, Jennifer Mankoff, and Jon E. Froehlich. In *Symposium on Computational Fabrication (SCF '22)*.
- [SIG.1] **SIG: Towards More Personal Health Sensing.** Junyi Zhu, [Liang He](#), Jun Nishida, Hamid Ghaednia, Cindy Hsin-Liu Kao, Jon E. Froehlich, Edward Jay Wang, and Stefanie Mueller. In *Extended Abstracts of the 2022 CHI Conference on Human Factors in Computing Systems (CHI EA '22)*.
- 2020 [EA.3] **PneuFetch: Supporting Blind and Visually Impaired People to Fetch Nearby Objects via Light Haptic Cues.** [Liang He](#), Ruolin Wang, Xuhai Xu. In *Proceedings of CHI '20 Extended Abstracts on Human Factors in Computing Systems (CHI EA '20)*.
- 2019 [P.6] **A Multi-Modal Approach for Blind and Visually Impaired Developers to Edit Webpage Designs.** Venkatesh Potluri, [Liang He](#), Christine Chen, Jon E. Froehlich, and Jennifer Mankoff. In *the 21st International ACM SIGACCESS Conference on Computers and Accessibility (ASSETS '19)*.
- 2017 [P.5] **TacTILE: A Preliminary Toolchain for Creating Accessible Graphics with 3D-Printed Overlays and Auditory Annotations.** [Liang He](#), Zijian Wan, Leah

Findlater, and Jon E. Froehlich. In *Poster Proceedings of the 19th International ACM SIGACCESS Conference on Computers & Accessibility (ASSETS '17)*.

[P.4] **Designing 3D-Printed Deformation Behaviors Using Spring-Based Structures: An Initial Investigation.** [Liang He](#), Huaishu Peng, Joshua Land, Mark D. Fuge, and Jon E. Froehlich. In *Adjunct Proceedings of the 30th Annual ACM Symposium on User Interface Software and Technology (UIST '17)*.

[P.3] **Early Exploration of Deformable Interactive Designs with 3D-Printed Springs.** [Liang He](#), Joshua Land, Huaishu Peng, Mark D. Fuge, and Jon E. Froehlich. In *Proceedings of the 1st Annual ACM Symposium on Computational Fabrication (SCF '17)*.

2016 [EA.2]  **ReWear: Early Explorations of a Modular Wearable Construction Kit for Young Children.** Majeed Kazemitabaar, [Liang He](#), Katie Wang, Chloe Aloimonos, Tony Cheng, and Jon E. Froehlich. In *Proceedings of CHI '16 Extended Abstracts on Human Factors in Computing Systems (CHI EA '16)*.

**Best Poster Award [Top 1%]**

[EA.1] **VRSurus: Enhancing Interactivity and Tangibility of Puppets in Virtual Reality.** Ruofei Du and [Liang He](#). In *Proceedings of CHI '16 Extended Abstracts on Human Factors in Computing Systems (CHI EA '16)*.

2012 [P.2] **E-Block: A Tangible Programming Tool for Children.** Danli Wang, Yang Zhang, Tianyuan Gu, Liang He, and Hongan Wang. In *Adjunct Proceedings of the 25th Annual ACM Symposium on User Interface Software and Technology (UIST '12)*.

[P.1] **TempoString: A Tangible Tool for Children's Music Creation.** [Liang He](#), Guang Li, Yang Zhang, Danli Wang, and Hongan Wang. In *Proceedings of the 14th International Conference on Ubiquitous Computing (UbiComp '12)*.

## Funding

2024 **Equitable and Personalized Treatment of Edema Through Wearable Textiles and Machine Learning-Based Pain Assessment.** [Liang He \(PI\)](#) and Sooyeon Jeong, \$192,000. *Institute for Physical Artificial Intelligence (IPAI), Purdue University*.

2023 **Exploratory SAIL Fund. Hacking, Designing, and Making.** [Liang He \(PI\)](#), \$2,667. *Purdue University*.

2023 **Assistive Haptic and Actuated Interface for People with Disability using Modular, Personalized On-body Robots.** [Liang He \(PI\)](#) and Huachao Mao, \$9,538. *Holistic Safety and Security (HSS) Research Impact Area, Purdue University*

## Honors and Awards

2024 **UIST 2024 Jury Best Poster Award**

- 2024 **IPAI Postdoctoral Research Award**, *Purdue University*
- 2024 **Purdue Polytechnic Institute Faculty Research Award**, *Purdue University*
- 2024 **Special Recognitions for Paper Reviews**, *UIST '24, CHI '24, DIS '24*
- 2023 **Special Recognitions for Paper Reviews**, *UIST '23, DIS '23, IMMUT, CHI '23*
- 2022 **Special Recognition for Paper Reviews**, *UIST '22, CHI '22*
- 2021 **Bob Bandes Memorial Honorable Mention Student Teaching Award (top 1%)**, *UW*
- 2021 **Special Recognition for Paper Reviews**, *UIST '21*
- 2020 **Special Recognition for Paper Reviews**, *UIST '20, CHI '20*
- 2019 **Winner**, *CHI '19 SV t-shirt design contest*
- 2018 **Finalist**, *Amazon Catalyst Award*
- 2017 **Best Paper Award (top 1%)**, *CHI '17*
- 2016 **Conference Travel Funding**, *Department of Computer Science, University of Maryland*
- 2016 **Best Late-Breaking Work Paper Award**, *CHI '16*
- 2016 **Dean's fellowship**, *Department of Computer Science, University of Maryland*
- 2015 **Dean's fellowship**, *Department of Computer Science, University of Maryland*
- 2015 **Paper Honorable Mentions Award (top 3%)**, *CHI '15*
- 2014 **Conference Travel Funding**, *School of Architecture, Carnegie Mellon University*
- 2014 **Department Scholarship**, *School of Architecture, Carnegie Mellon University*
- 2014 **Most Creative Award**, *UIST '14 Student Innovation Contest*
- 2014 **Winner**, *CHI '14 SV t-shirt design contest*
- 2013 **Department Scholarship**, *School of Architecture, Carnegie Mellon University*
- 2012 **Winner**, *G-Startup Seed Stage, Global Mobile Internet Conference '12*
- 2011 **Winner**, *Baidu User Experience contest*
- 2011 **Follow-up**, *Software Design, Microsoft Imagine Cup Local Final*
- 2009 **China National Scholarship (Top 1% nationwide)**, *China*

## Patent/Software Copyright

- 2013 [PA.1] **A Method and System for Children's Tangible Storytelling.**  
*Patent number: 2013100129910*
- 2010 [SC.1] **InkSound: A Pen-based System for Chinese Traditional Painting.**

## Invited Talks



- 2023 **Beyond Shape: Creating Interactive 3D Printable Objects.** *UW-Madison.*  
**Beyond Shape: Creating Interactive 3D Printable Objects.** *Purdue University.*  
**Beyond Shape: Creating Interactive 3D Printable Objects.** *Tsinghua University, virtual.*  
**Beyond Shape: Fabricating Kinetic Objects for Interactivity.** *Zhejiang Univ., China.*  
**Beyond Shape: Fabricating Kinetic Objects for Interactivity.** *Duke Kunshan, China.*  
**Beyond Shape: Fabricating Kinetic Objects for Interactivity.** *HCI Seminar, CSAIL, MIT.*
- 2022 **Beyond Shape.** *Georgia Tech.*  
**Beyond Shape.** *Hasso Plattner Institute, Germany.*
- 2021 **Beyond Shape.** *HCIL Brown-Bag Lunch. University of Maryland, College Park.*  
**ModElec.** *CSE Colloquium. University of Washington.*  
**Beyond Shape.** *HCI seminar invited by Ryo Suzuki. University of Calgary. Virtual.*  
**Kinetic Fab Research Overview.** *Lightning Talk. IWHEC 2021 affiliated forum. Virtual.*
- 2020 **3D Printing Electronics.** *HP 3D Print Lab.*  
**Designing, Controlling, and Fabricating In-Place Augmented Structures.** *UIST 2020 Doctoral Symposium. Virtual.*  
**Designing and Controlling On-Demand 3D Printable Structures to Support the Fabrication for Interactivity.** *DUB Doctoral Colloquium, UW, Seattle.*
- 2019 **Ondulé.** *Institute of Software, Chinese Academy of Sciences (ISCAS), China.*  
**Ondulé.** *HCI Lunch Talk. Stanford, CA.*  
**Making 3D-Printed Objects for Interactivity.** *Lightning Talk. UW CSE/MSR Summer Institute – Future of Fabrication, Blaine, WA.*
- 2018 **Modeling and Fabricating Interactivity and Creativity with Object Properties.** *UW CSE Colloquia – Computational Fabrication. Seattle.*  
**Fabricating High-Level Design Specifications with Low-Level Object Properties.** *Industry Affiliates Research Day. UW. Seattle.*
- 2016 **SqueezaPulse.** *Tech+Design: Interaction Design for a Purpose. UMD, College Park, MD.*  
**SqueezaPulse.** *HCIL's 33rd Annual Symposium. UMD, College Park, MD.*

## Guest Lectures/Workshops

- 2024 [L.7] **Intro to Physical Computing.** *Introduction to HCI, Information School, University of Maryland, College Park.*
- [L.6] **Digital Fabrication in HCI.** *Introduction to HCI, Department of Computer Science, University of Rochester.*

- [L.5] **Prototyping from Physical to Virtual to Physical.** *Introduction to HCI (CISCX82), Department of Computer Science, Univ. of Delaware.*
- 2022 [L.4] **Prototyping, Prototyping, Prototyping.** *Introduction to HCI (CISCX87), Department of Computer Science, Univ. of Delaware.*
- [L.3] **Build for Access.** *Introduction to Assistive Technology and Robotics (CNIT 581 AST). Department of Computer Information Technology, Purdue University.*
- [W.4] **CSNext Workshop.** *Mentoring four students from underrepresented groups. Computer Science & Engineering, UW.*
- 2020 [W.3] **3D Printed Electronics with ModElec.** *HP Labs.*
- 2019 [L.2] **Heuristic Evaluation.** *CSE 440A: Introduction to HCI. CSE, UW.*
- 2018 [W.2] **Video Making.** *CSE SkillShare Workshop, UW.*
- [W.1] **3D Modeling with Fusion 360.** *CSE 590A: Ubiquitous Computing, CSE, UW.*
- [L.1] **Laser Cutting.** *HCID 521, Human-Computer Interaction & Design, UW.*

## Teaching

- 2025 [TE.19] **CGT581: Interactive Prototyping & Digital Fabrication.** *CGT, Purdue. Instructor, taught 11 grad students, studio-based course*
- 2025 [TE.18] **CGT532: UX Design Graduate Studio (Cross-Channel).** *CGT, Purdue. Instructor, taught 11 grad students, studio-based course*
- 2024 [TE.17] **CGT27108: UX Design Learning Studio - Screen.** *CGT, Purdue. Instructor, taught 49 undergrad students, studio-based course*
- 2024 [TE.16] **CGT512: Foundational Readings of UX Design.** *CGT, Purdue. Instructor, taught 14 grad students*
- 2024 [TE.15] **CGT27208: UX Design Learning Studio (Cross-Channel).** *CGT, Purdue. Instructor, taught 46 undergrad students, studio-based course*
- 2024 [TE.14] **CGT532: UX Design Graduate Studio (Cross-Channel).** *CGT, Purdue. Instructor, taught 28 grad students, studio-based course*
- 2023 [TE.13] **CGT512: Foundational Readings of UX Design.** *CGT, Purdue. Instructor, taught 41 grad students*
- 2023 [TE.12] **CGT532: UX Design Graduate Studio (Cross-Channel).** *CGT, Purdue. Instructor, taught 28 grad students, studio-based course*
- 2022 [TE.11] **CGT116: Geometric Modeling for Visualization and Communication.** *CGT, Purdue. Instructor, taught 98 undergrad students, statewide and hybrid*
- 2021 [TE.10] **CSE 490: Physical Computing.** *CSE, UW. Remote teaching and hardware prototyping. Instructor: Jon E. Froehlich*



**Bob Bandes Memorial Honorable Mention Student Teaching Award [Top**



1%]

- 2020 [TE.9] **CSE 590A: Ubiquitous Computing.** CSE, UW. Course development and remote teaching. Instructor: Jon E. Froehlich
- 2019 [TE.8] **CSE 599U: Prototyping Interactive Systems.** CSE, UW.  
Instructor: Jon E. Froehlich
- [TE.7] **CSE 440A: Introduction to HCI.** CSE, UW.  
Instructor: Nigini Oliveira
- 2018 [TE.6] **CSE 440A: Introduction to HCI.** CSE, UW.  
Instructor: Nigini Oliveira
- [TE.5] **CSE 590A: Ubiquitous Computing.** CSE, UW. Course development  
Instructor: Jon E. Froehlich
- [TE.4] **HCID 521: Prototyping Studio.** HCID, UW. Course development  
Instructors: Jon E. Froehlich and Jennifer Mankoff
- 2016 [TE.3] **CMSC 250: Discrete Structures.** CS. UMD, College Park.
- [TE.2] **CMSC 132: Object-Oriented Programming II.** CS. UMD, College Park.
- 2015 [T.1] **CMSC 131: Object-Oriented Programming I.** CS. UMD, College Park.

## Services

### *Program Committee*

- 2025 **TEI 2026 Paper Chair**, *work-in-progress*
- 2025 **CHI 2025 Program Committee, Associate Chair**, *Blending Interaction: Engineering Interactive Systems & Tools subcommittee*
- 2024 **TEI 2024 Program Committee, Associate Chair**, *papers*
- 2024 **UIST 2024 Program Committee, Associate Chair**, *papers*
- 2024 **DIS 2024 Program Committee, Associate Chair**, *papers and pictorials*
- 2024 **ASSETS 2024 Program Committee, Associate Chair**, *papers, posters, and demos*
- 2024 **SIGGRAPH 2024 Posters Jury Committee**
- 2024 **SIGGRAPH 2024 Emerging Technologies Jury Committee**
- 2024 **CHI 2024 Program Committee, Associate Chair**, *Blending Interaction: Engineering Interactive Systems & Tools subcommittee*
- 2024 **CHI 2024 Student Design Competition Review Committee**
- 2023 **ASSETS 2023 Program Committee, Associate Chair**, *papers, posters, and demos*
- 2023 **DIS 2023 Program Committee, Associate Chair**, *papers and pictorials*

- 2023 **Invited Guest Editor for *Journal - CCF Transactions on Pervasive Computing & Interaction***
- 2023 **IDC 2023 Program Committee, Associate Chair, papers**
- 2022 **ASSETS 2022 Program Committee, Associate Chair, papers, posters, and demos**
- 2021 **ACHI 2021 Program Committee, Associate Chair, papers**
- 2021 **IDC 2021 Program Committee, Associate Chair, work-in-progress**
- 2021 **CHI 2021 Program Committee, Associate Chair, late-breaking work**
- 2020 **CHI 2020 Program Committee, Associate Chair, late-breaking work**
- 2019 **CHI 2019 Program Committee, Associate Chair, late-breaking work**

### ***Organizing Committee***

- 2024 **Student Innovation Contest co-chair, UIST 2024**
- 2023 **Posters & Demos co-chair, ASSETS 2023**
- 2023 **Experience Reports co-chair, ASSETS 2023**
- 2023 **Proceedings co-chair, UIST 2023**
- 2022 **Proceedings co-chair, UIST 2022**
- 2022 **Web and Graphic Design co-chair, ASSETS 2022**
- 2019 **Design and Web co-chair, UIST 2019**

### ***Reviewing***

250+ papers, **14 special recognitions for excellent review**

- 2024 **UIST '24, CHI '25, DIS '24, DIS '24, TEI '25, SIGGRAPH '24, ASSETS '24, ISMAR '24**
- 2023 **CHI '24, SCF '23, IDC '23, ASSETS '23, DIS '23, UIST '23, IEEE VR '24**
- 2022 **CHI '23, UIST '22, ASSETS '22, IEEE VR '23, IMWUT (November)**
- 2021 **CHI '22, UIST '21, DIS '21, SCF '21, CSCW (April), AHCI '21**
- 2020 **CHI '21, UIST '20, DIS '20, SCF '20**
- 2019 **CHI '20, UIST '19, WAC '19**
- 2018 **CHI '19**
- 2017 **CHI '18, TEI '18**
- 2016 **CHI '17, TEI '17, MobileHCI '16**
- 2015 **CHI '16**

### ***Other Services***

- 2024 **Session Chair, UIST 2024**

- 2023 **Session Chair**, *CHI 2023*
- 2022 **Session Chair**, *UIST 2022*
- 2021 **Session Chair**, *UIST 2021*
- 2017 **Student Volunteer**, *TEI 2017*
- 2015 **Student Volunteer**, *CHI 2015*
- 2014 **Student Volunteer**, *UIST 2014*
- 2014 **Student Volunteer**, *CHI 2014*
- 2012 **Student Assistant**, *the first China Symposium on HCI*

## Outreach

### **Collaborating with Seeed Studio to organize UIST 2024 Student Innovation Contest**

*Selected and created a custom hardware kit – Gen-M Kit – that contains over 80 programmable modules for physical computing and distributed the kits to eight student teams around the world.*

### **Leading the creation and maintenance of FabGalaxy (since 2018)**

*FabGalaxy is an online interactive visualization repository that provides a quick entry to fabrication research in human-computer interaction and computer graphics. This platform is hosted on the MIT's online repository for personal fabrication research which was created and maintained by HCI Engineering group, MIT CSAIL.*

## Press Coverages

- 2024 **From accessibility upgrades to a custom cat-food bowl, this mobile 3D printer can autonomously add features to a room.** *ScienceDaily.* [Link](#)
- 2024 **Meet MobiPrint: The smart 3D printer that can upgrade your home instantly.** *TechXplore.* [Link](#)
- 2024 **From accessibility upgrades to a custom cat-food bowl, this mobile 3D printer can autonomously add features to a room.** *UW News.* [Link](#)
- 2024 **3D printing on the move: UW device can map a room and print custom items in desired space.** *GeekWire.* [Link](#)

## Student Advised

- 2024–Present **Aezaz Ali.** *M.S. in Gaming at Purdue.*
- 2024–Present **Neo Agrawal.** *Senior in UX Design at Purdue.*
- 2024–Present **Thomas Carlock.** *M.S. in UX Design at Purdue.*
- 2024–Present **Jasmine Li.** *Senior in UX Design at Purdue.*

- 2023–Present **Amy Yu.** *M.S. in Information Visualization at Purdue.*
- 2023–Present **Haicheng Li.** *Junior in Computer and Information Technology at Purdue.*
- 2022–Present **Hsuanling Lee.** *Bachelor in Computer Engineering at Purdue.*
- 2023 **Riddhi Chaudhari.** *M.S. in User Experience Design at Purdue.*
- 2023 **Prithvi Manjunatha.** *M.S. in User Experience Design at Purdue.*
- 2023 **Chenxi Yang.** *Senior in Computer Science and Technology at Tsinghua University.*
- 2023 **Jacqueline Dong.** *M.F.A. in Communications Design at Pratt Institute.*
- 2023 **Zishuo Feng.** *M.S. in Computer and Information Technology at Purdue.*
- 2023 **Srishti Shekhar Agrawal.** *M.S. in User Experience Design at Purdue.*
- 2023 **Shrey Panchal.** *M.S. in User Experience Design at Purdue.*
- 2023 **Rohan Pant.** *M.S. in User Experience Design at Purdue.*
- 2022 **Maverick Broviak.** *Senior in Biomedical Engineering at Purdue.*
- 2022 **Emily Ann Testin.** *Senior in Mechanical Engineering at Purdue.*
- 2022 **Liwen He.** *M.S. in Industrial Design at Beihang University, China.*
- 2022 **Yifan Li.** *Senior in Architecture at Southeast University, China.*
- 2021–2022 **Daniel Campos Zamora.** *Ph.D. in CSE at UW.*
- 2021 **Hongnan Lin.** *Ph.D. in Design at Georgia Tech; now postdoc at ISCAS.*
- 2020–2021 **Yueqian Zhang.** *Undergraduate in CSE at UW; now engineer at Roblox.*
- 2020–2021 **Xia Su.** *M.S. in Architecture at Tsinghua; now Ph.D. in CSE at UW.*
- 2020–2021 **Xiyuan Shen.** *Undergradudate in Media Art at Tsinghua; now Ph.D. in CSE at UW.*
- 2020–2021 **Arjun Simha.** *High school student; now undergrad in EE at UW.*
- 2019–2021 **Jessica Chin.** *Undergradudate in Psychology at UW; now at Meta.*
- 2020 **Yawen Zheng.** *Undergradudate in Media Art at Tsinghua; now M.S. at Tsinghua.*
- 2020 **Yuebing Liang.** *M.S. in Architecture at Tsinghua; now Ph.D. at Hong Kong Univ.*
- 2019 **Venkatesh Potluri.** *Ph.D. in CSE at UW; now Assistant Professor at UMich.*
- 2019 **Sophie Tian.** *Undergrad in CSE at UW; now software engineer at Microsoft.*
- 2018–2019 **Michelle Lin.** *Undergrad in CSE at UW; now grad in CSE at UW.*
- 2017 **Joshua Land.** *Undergrad in Mech Engineering at UMD; now engineer at Appian.*
- 2012 **Muyan Li.** *Undergrad at Beihang; now software engineer at UiPath.*
- 2012 **Yang Zhang.** *Undergrad at Beihang; now Assistant Professor at UCLA.*
- 2012 **Keqin Dou.** *Undergrad at Univ. of Science and Technology Beijing; now regional director at Fintopia.*